## **MICROWAVE POWER GaAs FET**

## Internally Matched Power GaAs FETs (X, Ku-Band)

## Features

- High power
  - $P_{1dB}$  = 39.5 dBm at 12.7 GHz to 13.2 GHz
- High gain
- G<sub>1dB</sub> = 5.0 dB at 12.7 GHz to 13.2 GHz
  Broadband internally matched
- Hermetically sealed package

#### RF Performance Specifications (T<sub>a</sub> = 25°C)

Characteristic	Symbol	Condition	Unit	Min.	Тур.	Max
Output Power at 1dB Compression Point	P <sub>1dB</sub>	V <sub>DS</sub> = 9V f = 12.7 - 13.2 GHz	dBm	38.5	39.5	-
Power Gain at 1dB Compression Point	G <sub>1dB</sub>		dB	4.0	5.0	-
Drain Current	I <sub>DS</sub>		Α	-	3.4	4.4
Power Added Efficiency	$\eta_{\text{add}}$		%	-	20	-
Channel-Temperature Rise	$\Delta T_{ch}$	$V_{DS} \times I_{DS} \times R_{th (c-c)}$	°C	-	-	80

## Electrical Characteristics (T<sub>a</sub> = 25°C)

Characteristic	Symbol	Condition	Unit	Min.	Typ.	Max.
Transconductance	gm	V <sub>DS</sub> = 3V I <sub>DS</sub> = 4.0A	mS	-	2400	-
Pinch-off Voltage	V <sub>GSoff</sub>	V <sub>DS</sub> = 3V I <sub>DS</sub> = 120 mA	V	-2	-3.5	-5
Saturated Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 3V V <sub>GS</sub> = 0V	Α	-	8.0	10.4
Gate-Source Breakdown Voltage	V <sub>GSO</sub>	I <sub>GS</sub> = -120 μA	V	-5	-	-
Thermal Resistance	R <sub>th (c-c)</sub>	Channel to Case	°C/W	-	1.6	2.5

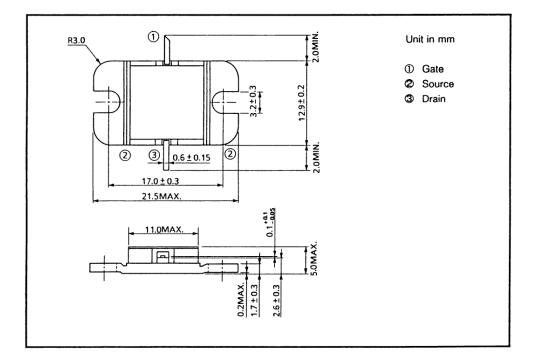
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# Absolute Maximum Ratings (T<sub>a</sub> = 25°C)

Characteristic	Symbol	Unit	Rating
Drain-Source Voltage	V <sub>DS</sub>	v	15
Gate-Source Voltage	V <sub>GS</sub>	v	-5
Drain Current	I <sub>D</sub>	А	10.4
Total Power Dissipation ( $T_c = 25^{\circ}C$ )	PT	w	60
Channel Temperature	T <sub>ch</sub>	°C	175
Storage Temperature	T <sub>stg</sub>	°C	-65 ~ 175

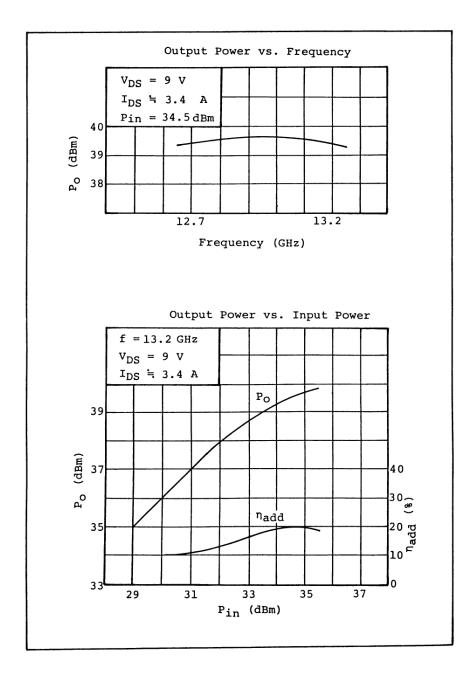
## Package Outline (2-11C1B)



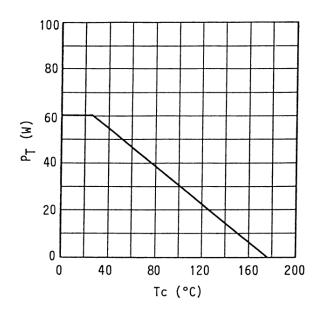
## Handling Precautions for Packaged Type

Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.

## **RF Performances**



# Power Dissipation vs. Case Temperature



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TIM1213-8 S-Parameters (Magn. and Angles)



